![Texas Instruments logo] **TEXAS INSTRUMENTS**

| application |
| INFO |
| available |

UC1706
UC2706
UC3706

Dual Output Driver

FEATURES

- Dual, 1.5A Totem Pole Outputs

- 40nsec Rise and Fall into 1000pF

- Parallel or Push-Pull Operation

- Single-Ended to Push-Pull Conversion

- High-Speed, Power MOSFET Compatible

- Low Cross-Conduction Current Spike

- Analog, Latched Shutdown

- Internal Deadband Inhibit Circuit

- Low Quiescent Current

- 5 to 40V Operation

- Thermal Shutdown Protection

- 16-Pin Dual-In-Line Package

- 20-Pin Surface Mount Package

DESCRIPTION

The UC1706 family of output drivers are made with a high-speed Schottky process to interface between low-level control functions and high-power switching devices - particularly power MOSFET's. These devices implement three generalized functions as outlined below.

First: They accept a single-ended, low-current digital input of either polarity and process it to activate a pair of high-current, totem pole outputs which can source or sink up to 1.5A each.

Second: They provide an optional single-ended to push-pull conversion through the use of an internal flip-flop driven by double-pulse-suppression logic. With the flip-flop disabled, the outputs work in parallel for 3.0A capability.

Third: Protection functions are also included for pulse-by-pulse current limiting, automatic deadband control, and thermal shutdown.

These devices are available in a two-watt plastic "bat-wing" DIP for operation over a 0°C to 70°C temperature range and, with reduced power, in a hermetically sealed cerdip for -55°C to +125°C operation. Also available in surface mount Q and L packages.
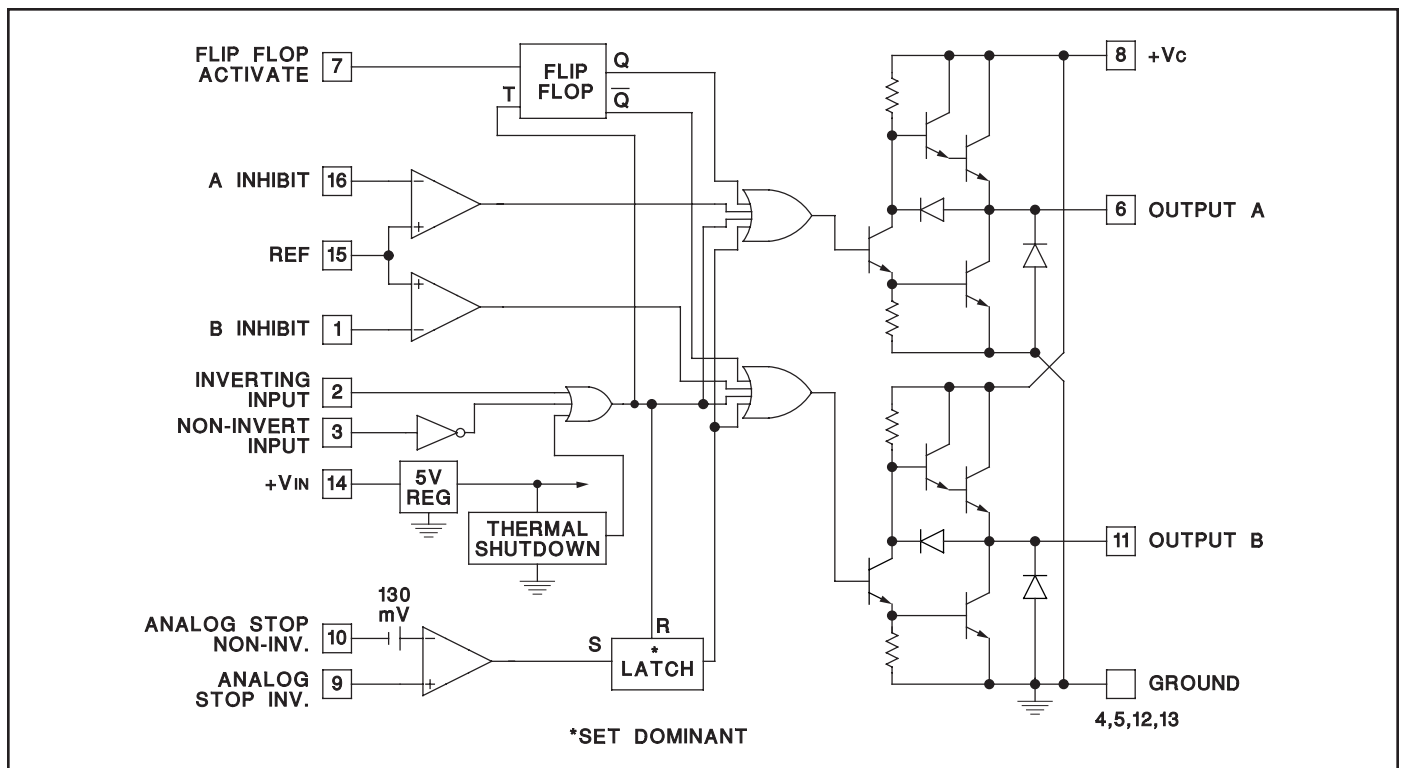
TRUTH TABLE

INV	N.I	OUT
H	H	L
L	H	H
H	L	L
L	L	L

$OUT = \overline{INV}$ and N.I.

$\overline{OUT} = INV$ or $\overline{N.I.}$

BLOCK DIAGRAM

ABSOLUTE MAXIMUM RATINGS

```
. . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . .  N--Pkg . . . . . . . . . . . . . .  J--Pkg
```

Supply Voltage, V_{IN} . . . . 40V 40V
Collector Supply Voltage, V_C . . . . 40V 40V
Output Current (Each Output, Source or Sink)
Steady--State . . . . ±500mA . . . . ±500mA
Peak Transient . . . . ±1.5A . . . . ±1.0A
Capacitive Discharge Energy . . . . 20μJ 15μJ
Digital Inputs . . . . 5.5V 5.5V
Analog Stop Inputs . . . . V_{IN}. . . . . V_{IN}
Power Dissipation at T_A = 25°C (See Note) . . . . . . 2W 1W
Power Dissipation at T (Leads/Case) = 25°C 5W 2
(See Note)
Operating Temperature Range . . . . --55°C to +125°C
Storage Temperature Range. . . . . --65°C to +150°C
Lead Temperature (Soldering, 10 Seconds) . . . . 300°C

Note: All voltages are with respect to the four ground pins which must be connected together. All currents are positive into, negative out of the specified trerminal. Consult Packaging sections of the Databook for thermal limitations and considerations of package.

CONNECTION DIAGRAMS

DIL-16, SOIC-16 (TOP VIEW)
J or N Package, DW Package

B INHIBIT	1	16	A INHIBIT
INV. INPUT	2	15	INHIBIT REF
N.I. INPUT	3	14	V_{IN}
GROUND	4	13	GROUND
GROUND	5	12	GROUND
A OUTPUT	6	11	B OUTPUT
FLIP/FLOP	7	10	STOP NON-INV.
V_C	8	9	STOP INV.

PLCC-20, LCC-20 (TOP VIEW)
Q, L Packages
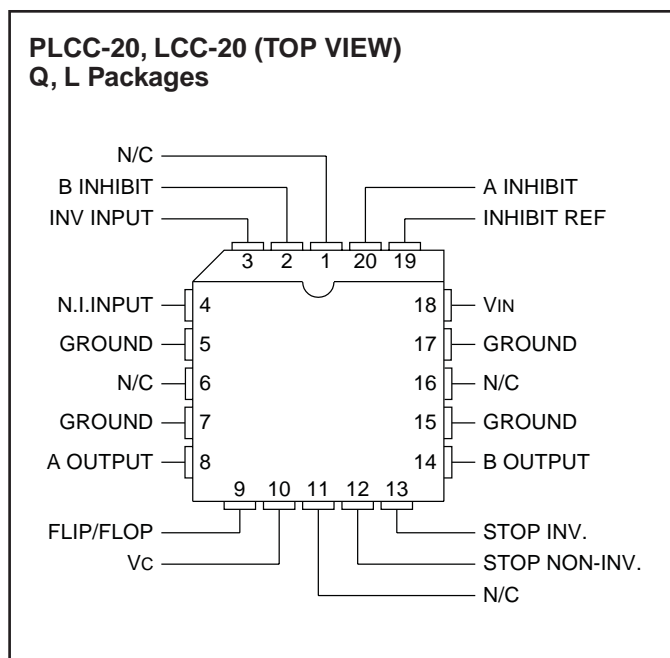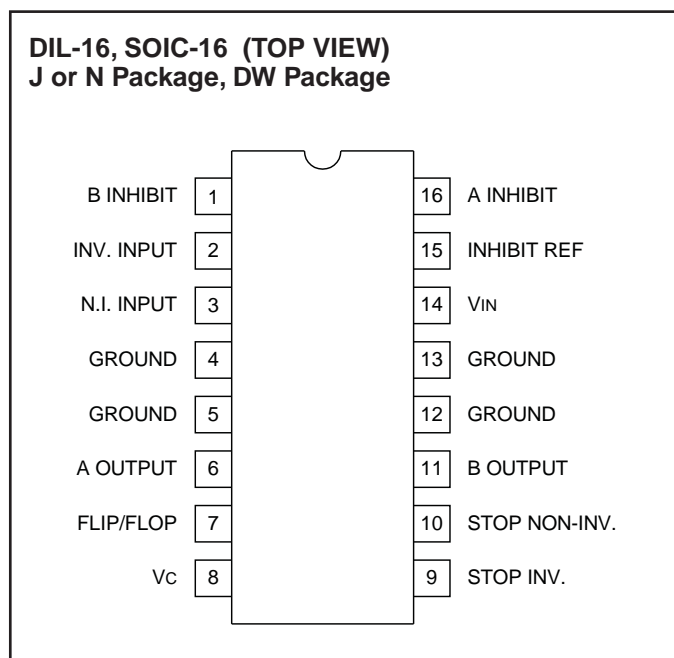
Note: All four ground pins must be connected to a common ground.

ELECTRICAL CHARACTERISTICS:
Unless otherwise stated, these specifications apply for T_A = –55°C to +125°C for the UC1706, –25°C to +85°C for the UC2706 and 0°C to +70°C for the UC3706; V_{IN} = V_C = 20V. T_A = T_J.

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
V_{IN} Supply Current	V_{IN} = 40V		8	10	mA
V_C Supply Current	V_C = 40V, Outputs Low		4	5	mA
V_C Leakage Current	V_{IN} = 0, V_C = 30V, No Load		.05	0.1	mA
Digital Input Low Level				0.8	V
Digital Input High Level		2.2			V
Input Current	V_I = 0		–0.6	–1.0	mA
Input Leakage	V_I = 5V		.05	0.1	mA

ELECTRICAL CHARACTERISTICS: Unless otherwise stated, these specifications apply for T_A = –55°C to +125°C for the UC1706, –25°C to +85°C for the UC2706 and 0°C to +70°C for the UC3706; V_{IN} = V_C = 20V. T_A = T_J.

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Output High Sat., V_C-V_O	I_O = -50mA			2.0	V
Output Low Sat., V_O	I_O = 50mA			0.4	V
	I_O = 500mA			2.5	V
Inhibit Threshold	V_{REF} = 0.5V	0.4		0.6	V
	V_{REF} = 3.5V	3.3		3.7	V
Inhibit Input Current	V_{REF} = 0		–10	–20	µA
Analog Threshold	V_{CM} = 0 to 15V, for the UC2706 and UC3706	100	130	160	mV
	V_{CM} = 0 to 15V, for the UC1706	80	130	160	mV
Input Bias Current	V_{CM} = 0		–10	–20	µA
Thermal Shutdown			155		°C

TYPICAL SWITCHING CHARACTERISTICS: V_{IN} = V_C = 20V, T_A = 25°C. Delays measured to 10% output change.

PARAMETERS	TEST CONDITIONS	OUTPUT C_L =			UNITS
From Inv. Input to Output:		open	1.0	2.2	nF
Rise Time Delay		110	130	140	ns
10% to 90% Rise		20	40	60	ns
Fall Time Delay		80	90	110	ns
90% to 10% Fall		25	30	50	ns
From N. I. Input to Output:					
Rise Time Delay		120	130	140	ns
10% to 90% Rise		20	40	60	ns
Fall Time Delay		100	120	130	ns
90% to 10% Fall		25	30	50	ns
V_C Cross-Conduction Current Spike Duration	Output Rise	25			ns
	Output Fall	0			ns
Inhibit Delay	Inhibit Ref. = 1V, Inhibit Inv. = 0.5 to 1.5V	250			ns
Analog Shutdown Delay	Stop Non-Inv. = 0V, Stop Inv. = 0 to 0.5V	180			ns

CIRCUIT DESCRIPTION

Outputs

The totem-pole outputs have been designed to minimize cross-conduction current spikes while maximizing fast, high-current rise and fall times. Current limiting can be done externally either at the outputs or at the common V_C pin. The output diodes included have slow recovery and should be shunted with high-speed external diodes when driving high-frequency inductive loads.

Flip/Flop

Grounding pin 7 activates the internal flip-flop to alternate the two outputs. With pin 7 open, the two outputs operate simultaneously and can be paralleled for higher current operation. Since the flip-flop is triggered by the digital input, an off-time of at last 200nsec must be provided to allow the flip/flop to change states. Note that the circuit logic is configured such that the "OFF" state is defined as the outputs low.

Digital Inputs

With both an inverting and non-inverting input available, either active-high or active-low signals may be accepted. These are true TTL compatible inputs—the threshold is approximately 1.2V with no hysteresis; and external pull-up resistors are not required.

Inhibit Circuit

Although it may have other uses, this circuit is included to eliminate the need for deadband control when driving relatively slow bipolar power transistors. A diode from each inhibit input to the opposite power switch collector will keep one output from turning-on until the other has turned-off. The threshold is determined by the voltage on pin 15 which can be set from 0.5 to 3.5V. When this circuit is not used, ground pin 15 and leave 1 and 16 open.

CIRCUIT DESCRIPTION (cont.)

Analog Shutdown

This circuit is included to get a latched shutdown as close to the outputs as possible, from a time standpoint. With an internal 130mV threshold, this comparator has a common-mode range from ground to (VIN – 3V). When not used, both inputs should be grounded. The time required for this circuit to latch is inversely proportional to the amount of overdrive but reaches a minimum of 180nsec. As with the flip-flop, an input off-time of at least 200nsec is required to reset the latch between pulses.

Supply Voltage

With an internal 5V regulator, this circuit is optimized for use with a 7 to 40V supply; however, with some slight response time degradation, it can also be driven from 5V. When VIN is low, the entire circuit is disabled and no current is drawn from VC. When combined with a UC1840 PWM, the Driver Bias switch can be used to supply VIN to the UC1706. VIN switching should be fast as if VC is high, undefined operation of the outputs may occur with VIN less than 5V.
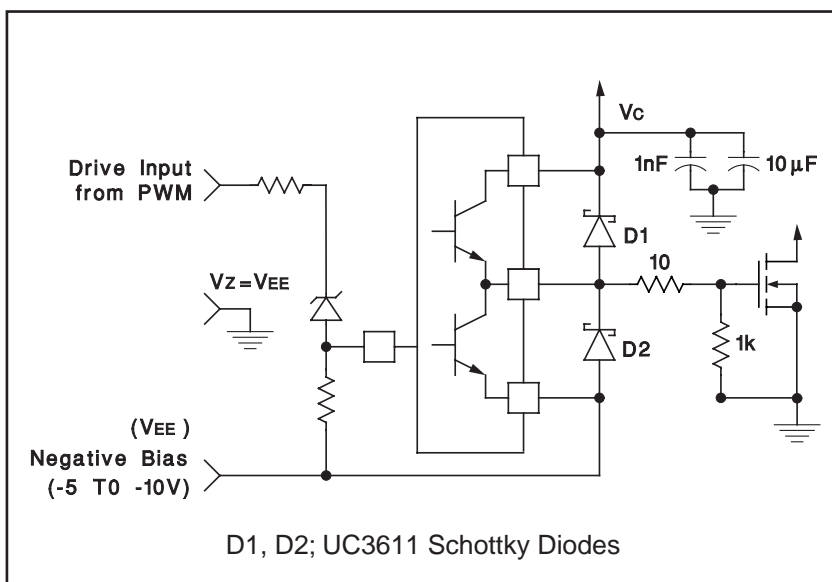
Thermal Considerations

Should the chip temperature reach approximately 155°C, a parallel, non--inverting input is activated driving both outputs to the low state.
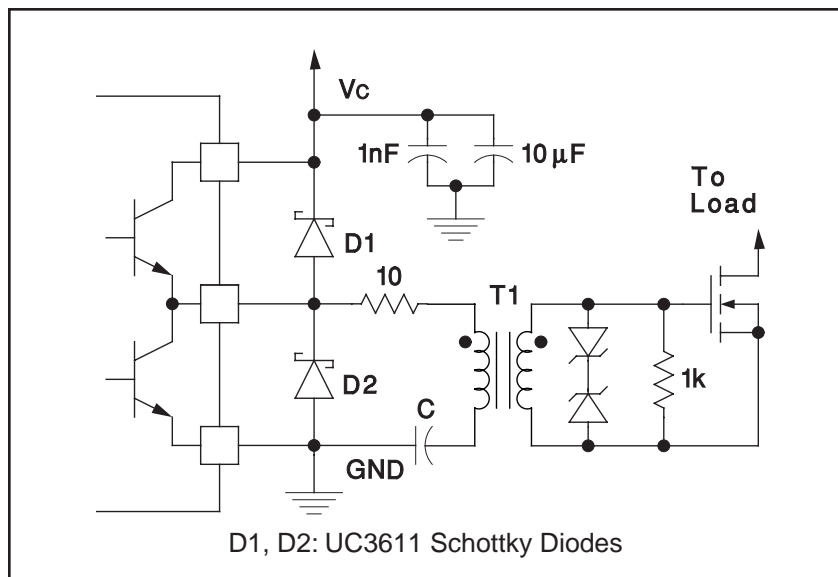
APPLICATIONS
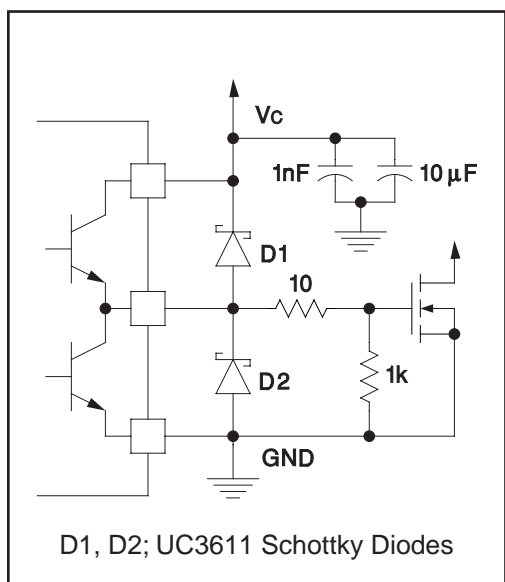
D1, D2; UC3611 Schottky Diodes
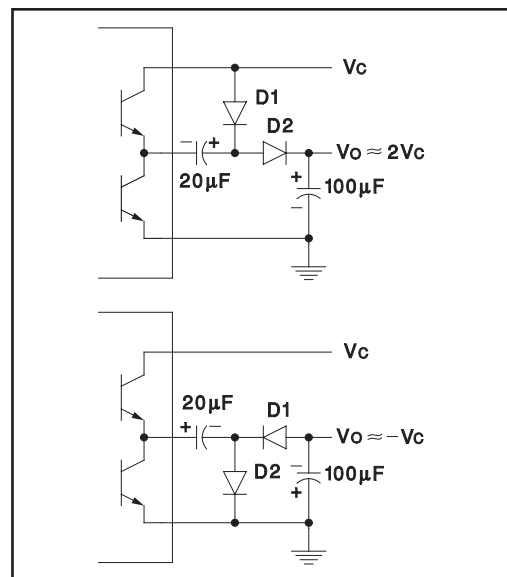
Power MOSFET Drive Circuit

D1, D2; UC3611 Schottky Diodes

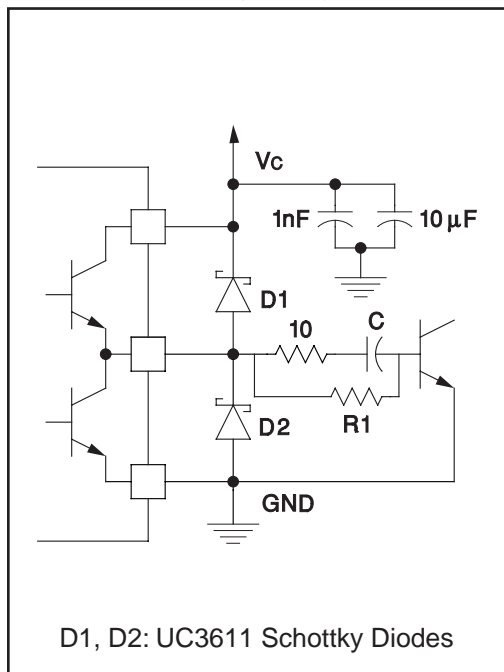**Power MOSFET Drive Circuit Using Negative Bias Voltage and Level Shifting to Ground Referenced PWMs**

D1, D2: UC3611 Schottky Diodes

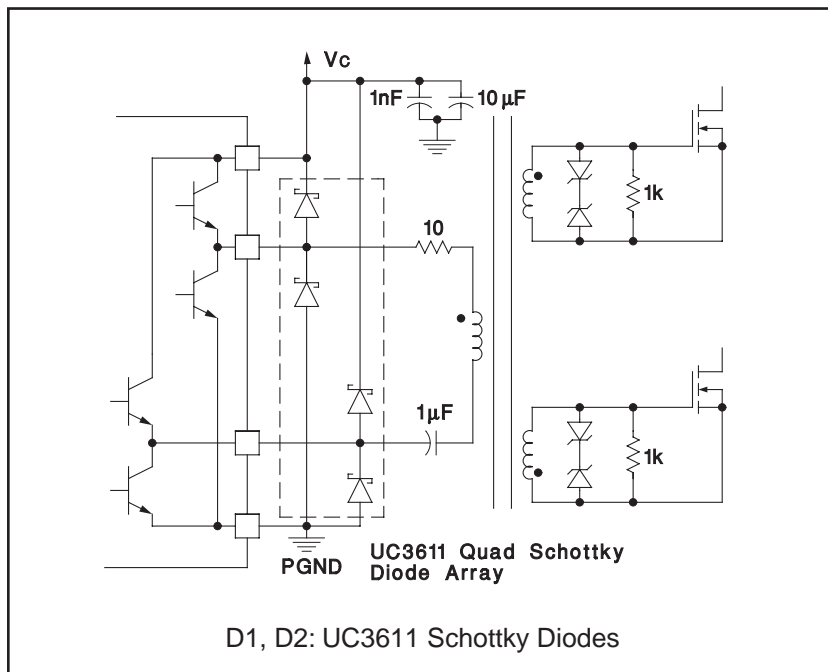**Transformer Coupled MOSFET Drive Circuit**
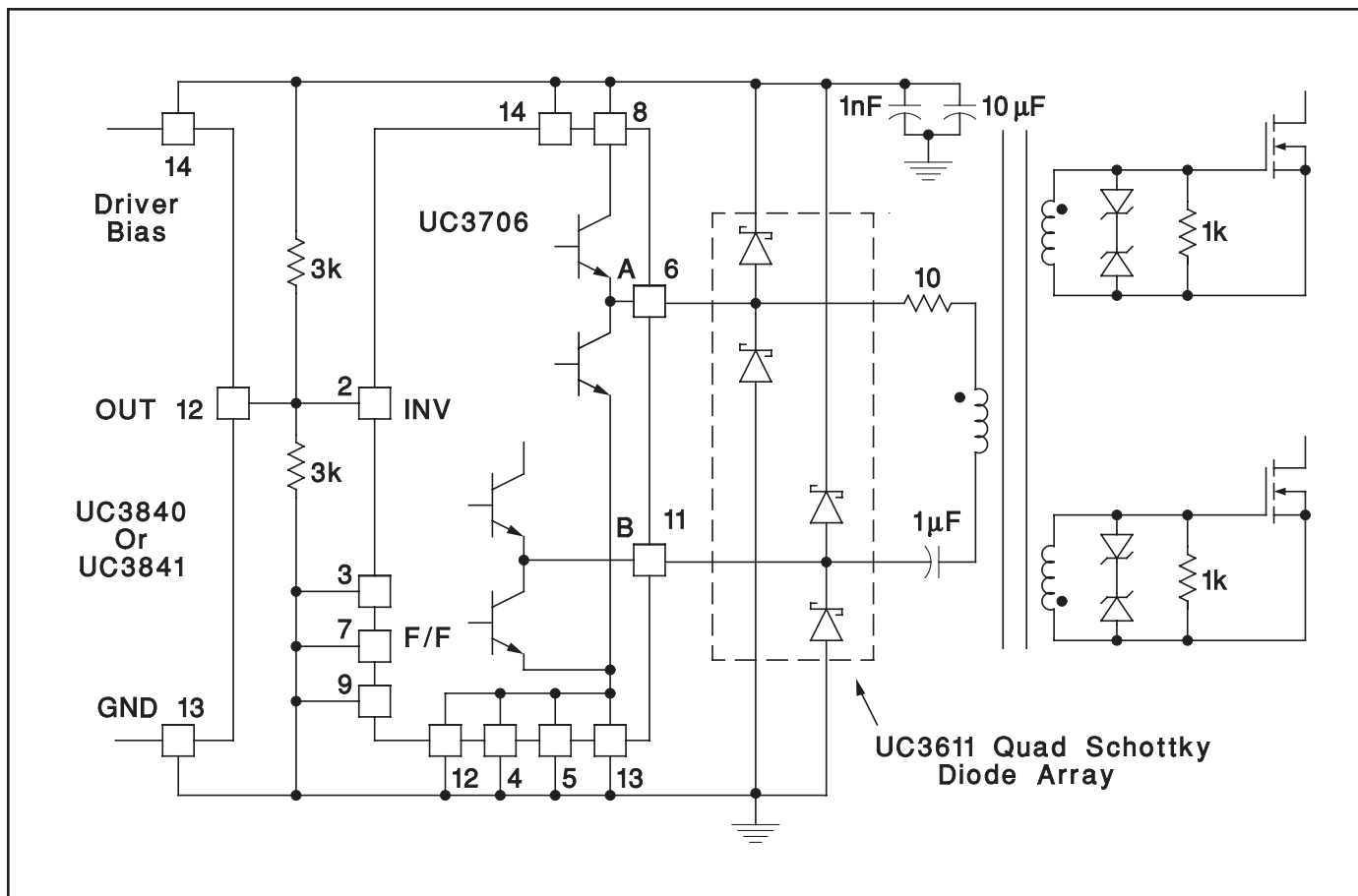

Charge Pump Circuits

APPLICATIONS (cont'd)

D1, D2: UC3611 Schottky Diodes

Power Bipolar Drive Circuit

D1, D2: UC3611 Schottky Diodes

Transformer Coupled Push-Pull MOSFET Drive Circuit

UC3706 Converts Single Output PWMs to High Current Push-Pull Configuration

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/ Ball Finish	MSL Peak Temp [3]	Samples (Requires Login)
5962-89611012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	Add to cart
5962-8961101EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	Add to cart
UC1706J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	Add to cart
UC1706J883B	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	Add to cart
UC1706L	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	Add to cart
UC2706DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Add to cart
UC2706DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Add to cart
UC2706J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	Add to cart
UC2706N	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
UC2706NG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
UC3706DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Add to cart
UC3706DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Add to cart
UC3706DWTR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Add to cart
UC3706DWTRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Add to cart
UC3706J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	Add to cart
UC3706N	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
UC3706NG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF UC1706, UC2706, UC2706M, UC3706, UC3706M :

● Catalog: UC3706, UC2706, UC3706M, UC3706

● Military: UC2706M, UC1706, UC1706

NOTE: Qualified Version Definitions:

   ● Catalog - TI's standard catalog product

   ● Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC3706DWTR	SOIC	DW	16	2000	330.0	16.4	10.85	10.8	2.7	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC3706DWTR	SOIC	DW	16	2000	346.0	346.0	33.0

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		**Applications**	
Audio	www.ti.com/audio	Communications and Telecom	www.ti.com/communications
Amplifiers	amplifier.ti.com	Computers and Peripherals	www.ti.com/computers
Data Converters	dataconverter.ti.com	Consumer Electronics	www.ti.com/consumer-apps
DLP® Products	www.dlp.com	Energy and Lighting	www.ti.com/energy
DSP	dsp.ti.com	Industrial	www.ti.com/industrial
Clocks and Timers	www.ti.com/clocks	Medical	www.ti.com/medical
Interface	interface.ti.com	Security	www.ti.com/security
Logic	logic.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Power Mgmt	power.ti.com	Transportation and Automotive	www.ti.com/automotive
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com	Wireless	www.ti.com/wireless-apps
RF/IF and ZigBee® Solutions	www.ti.com/lprf		

TI E2E Community Home Page   e2e.ti.com